Chip Power Bead for Consumer equipment & Industrial equipment BLE32PN□□□SN1□ Reference Specification

1.Scope

This reference specification applies to Chip Power Bead BLE32PN SN Series.

1.1 Specific applications:

- Power equipment: Products that can be used in power equipment such as renewable energy equipment, energy storage
 equipment and EV charging equipment and whose functions are not directly related to the protection of human life and
 property.
- Industrial equipment: Products that can be used in industrial equipment such as base stations, manufacturing equipment, industrial robotics equipment, and measurement equipment, and whose functions do not directly relate to the protection of human life and property.
- Medical equipment (GHTF Class C) *Except for implant/surgery/auto injector: Products that can be used for medical equipment of Class C of the international classification class GHTF and whose malfunction is considered to pose a relatively high risk to the human body.
- Medical equipment (GHTF Class A and B): Products that can be used for medical equipment regulated by Class A and Class B of the international classification class GHTF and whose functions do not directly relate to the protection of human life and property.
- Consumer equipment: Products that can be used in consumer equipment such as home appliances, audio/visual equipment, communication equipment, information equipment, office equipment, and household robotics, and whose functions are not directly related to the protection of human life and property.

1.2 Unsuitable application:

Applications listed in "Limitation of applications" in this reference specification.

WE DISCLAIM ANY LOSS AND DAMAGES ARISING FROM OR IN CONNECTION WITH THE PRODUCTS INCLUDING BUT NOT LIMITED TO THE CASE SUCH LOSS AND DAMAGES CAUSED BY THE UNEXPECTED ACCIDENT, IN EVENT THAT THE PRODUCT IS APPLIED FOR THE PURPOSE WHICH IS SPECIFIED ABOVE AS THE UNSUITABLE APPLICATION FOR THE PRODUCT.

2. Part Numbering

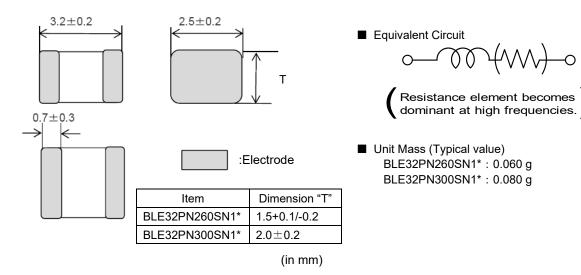
(ex.)	BL	<u>E</u>	32	PN	300	S	N	1_	L
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)
(1)Product ID					(6)F	Perforr	nance		
	(2)Ty	ре				(7)	Catego	ry	
	(3)Dir	mensio	n (L×W	/)		(8)	lumbe	rs of C	Circuit
	(4)Ch	aracte	ristics			(9)F	ackag	jing (L	:Taping)
	(5)Ty	pical Ir	npedan	ice at 10	00MHz				

3. Rating

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	Customer Part Number	MURATA Part Number	Impedance (Ω (at 100MHz,Under Sta Testing C	ndard	Rated Current (A)	(mΩ) Initial	sistance) max. Values After Testing	Remark
		BLE32PN260SN1L	26±10	26	10	1.6	2.1	For DC
	•	BLE32PN300SN1L	30±10	30	10	1.6	2.1	power line

[•] Operating Temperature: -55°C to +125°C • Storage Temperature: -55°C to +125°C

4. Style and Dimensions



5. Marking

No marking.

6. Standard Testing Conditions

< Unless otherwise specified > Temperature : Ordinary Temp. (15 °C to 35 °C)

Humidity: Ordinary Humidity (25%(RH) to 85%(RH))

< In case of doubt >

Temperature : 20°C±2 °C Humidity : 60%(RH) to 70%(RH)

Atmospheric pressure: 86kPa to 106kPa

7. Specifications

7-1. Electrical Performance

No.	Item	Specification	Test Method	
7-1-1	Impedance	Meet item 3.	Measuring Frequency : 100MHz±1MHz	
			Measuring Equipment :KEYSIGHT 4291A or the equivalent	
			Test Fixture : KEYSIGHT 16192A or the equivalent	
7-1-2	DC Resistance	Meet item 3.	Measuring Equipment : Digital multi meter	
			* Except resistance of the Substrate and Wire	

7-2. Mechanical Performance

No.	chanical Perform	Specification	Test Method
	Appearance and Dimensions	Meet item 4.	Visual Inspection and measured with Slide Calipers.
7-2-2	Bonding Strength	Meet Table 1. Table 1 Appearance No damage Impedance Change Within ±30% (at 100MHz) DC Resistance Meet item 3.	It shall be soldered on the substrate. Applying Force(F): 9.8N Applying Time: 5s±1s Applied direction:Parallel to substrate Side view F Substrate
7-2-3	Bending Strength		It shall be soldered on the substrate. Substrate: Glass-epoxy 100mm×40mm×1.0mm Deflection: 2.0mm Speed of Applying Force: 0.5mm/s Keeping Time: 30s
7-2-4	Vibration		It shall be soldered on the substrate. Oscillation Frequency: 10Hz to 2000Hz to 10Hz for 20 min Total Amplitude: 3.0mm or Acceleration amplitude 245m/s² whichever is smaller. Testing Time: A period of 2 hours in each of 3 mutually perpendicular directions. (Total 6 h)
7-2-5	Resistance to Soldering Heat		Pre-Heating: 150°C±10°C, 60s~90s Solder: Sn-3.0Ag-0.5Cu Solder Temperature: 270°C±5°C Immersion Time: 10s±0.5s Immersion and emersion rates: 25mm/s Then measured after exposure in the room condition for 48h±4h.
7-2-6	Drop	Products shall be no failure after tested.	It shall be dropped on concrete or steel board. Method : free fall Height : 75cm Attitude from which the product is dropped : 3 direction The number of times : 3 times for each direction (Total 9 times)
7-2-7	Solderability	The electrodes shall be at least 95% covered with new solder coating.	Flux: Ethanol solution of rosin,25(wt)% Pre-Heating: 150°C±10°C, 60s~90s Solder: Sn-3.0Ag-0.5Cu Solder Temperature: 240°C±5°C Immersion Time: 4s±1s Immersion and emersion rates: 25mm/s



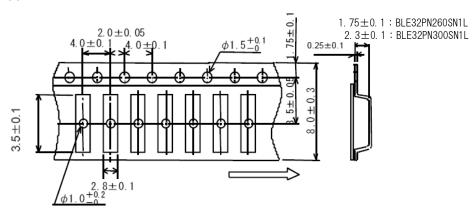
7-3. Environmental Performance

It shall be soldered on the substrate.

No.	Item	Specification	Test Method
7-3-1	Temperature Cycle	Meet Table 1.	1 cycle: 1 step: -55 °C(+0 °C,-3 °C) / 30min±3min 2 step: Ordinary temp. / 10min to 15min 3 step: +125 °C(+3 °C,-0 °C) / 30min±3min 4 step: Ordinary temp. / 10min to 15min Total of 100 cycles Then measured after exposure in the room condition for 48h±4h.
7-3-2	Humidity		Temperature: 40°C±2°C Humidity: 90%(RH) to 95%(RH) Time: 1000h(+48h,-0h) Then measured after exposure in the room condition for 48h±4h.
7-3-3	Heat Life		Temperature: 125°C±3°C Applying Current: Rated Current Time: 1000h(+48h,-0h) Then measured after exposure in the room condition for 48h±4h.
7-3-4	Cold Resistance		Temperature : -55±2°C Time : 1000h(+48h,-0h) Then measured after exposure in the room condition for 48h±4h.

8. Specification of Packaging

8-1. Appearance and Dimensions (8mm-wide plastic tape)



(in mm)

*Dimension of the Cavity is measured at the bottom side.

(1) Taping

Products shall be packaged in the each embossed cavity of 8mm-wide, 4mm-pitch and plastic tape continuously and sealed by cover tape.

- (2) Sprocket hole: The sprocket holes are to the right as the tape is pulled toward the user.
- (3) Spliced point : The cover tape has no spliced point.
- (4) Missing components number

Missing components number within 0.025% of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

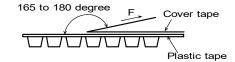
8-2. Tape Strength

(1)Pull Strength

Plastic tape	5N min.
Cover tape	10N min.

(2) Peeling off force of Cover tape

0.2N to 0.7N (Minimum value is typical.) *Speed of Peeling off:300mm/min



8-3. Taping Condition

(1) Standard quantity per reel

Quantity per 180mm reel: 1500 pcs. / reel

- (2) There shall be leader-tape (cover tape only and empty tape) and trailer- tape (empty tape) as follows.
- (3) Marking for reel

The following items shall be marked on a label and the label is stuck on the reel.

(Customer part number, MURATA part number, Inspection number (*1), RoHS marking (*2), Quantity, etc)

*1) « Expression of Inspection No. »

□□ 0000 <u>×××</u>

(1) Factory Code

(2) Date First digit

Year / Last digit of year

Second digit Month / Jan. to Sep. \rightarrow 1 to 9, Oct. to Dec. \rightarrow O, N, D

Third, Fourth digit: Day

(3) Serial No.

*2) « Expression of RoHS marking »

ROHS $-\frac{Y}{(1)}(\underline{\Delta})$

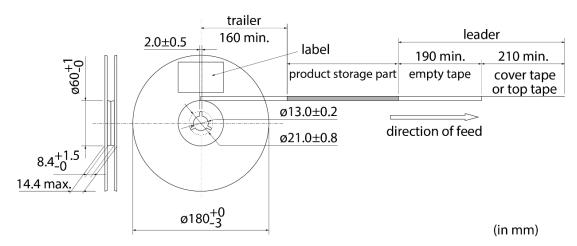
- (1) RoHS regulation conformity parts.(2) MURATA classification number
- (4) Outside package

These reels shall be packed in the corrugated cardboard package and the following items shall be marked on a label and the label is stuck on the box.

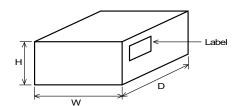
(Customer name, Purchasing order number, Customer part number, MURATA part number,

RoHS marking (*2), Quantity, etc)

(5) Dimensions of reel and taping (leader-tape, trailer-tape)



8-4. Specification of Outer Case



Outer Case Dimensions (mm)		nsions	Standard Reel Quantity in Outer Case	
W	D	Н	(Reel)	
186	186	93	5	

^{*} Above Outer Case size is typical. It depends on a quantity of an order.



9. **A**Caution

9-1. Surge current

Excessive surge current (pulse current or rush current) than specified rated current applied to the product may cause a critical failure, such as an open circuit, burnout caused by excessive temperature rise.

Please contact us in advance in case of applying the surge current.

9-2. Limitation of Applications

The products listed in the reference specification (hereinafter the product(s) is called as the "Product(s)") are designed and manufactured for applications specified in the reference specification (hereinafter called as the "Specific Application").

We shall not warrant anything in connection with the Products including fitness, performance, adequateness, safety, or quality, in the case of applications listed in from (1) to (11) written at the end of this precautions, which may generally require high performance, function, quality, management of production or safety. Therefore, the Product shall be applied in compliance with the specific application.

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- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Power plant control equipment
- (5) Medical equipment
- (6) Transportation equipment
- (7) Traffic control equipment
- (8) Disaster prevention/security equipment
- (9) Industrial data-processing equipment
- (10) Combustion/explosion control equipment
- (11) Equipment with complexity and/or required reliability equivalent to the applications listed in the above.

For exploring information of the Products which will be compatible with the particular purpose other than those specified in the reference specification, please contact our sales offices, distribution agents, or trading companies with which you make a deal, or via our web contact form.

Contact form: https://www.murata.com/contactform

* We may design and manufacture particular Products for applications listed in (1) to (11). Provided that, in such case we shall unambiguously specify such Specific Application in the reference specification without any exception. Therefore, any other documents and/or performances, whether exist or non-exist, shall not be deemed as the evidence to imply that we accept the applications listed in (1) to (11).

9-3. Corrosive gas

Please refrain from use since contact with environments with corrosive gases (sulfur gas [hydrogen sulfide, sulfur dioxide, etc.], chlorine, ammonia, etc.) or oils (cutting oil, silicone oil, etc.) that have come into contact with the previously stated corrosive gas environment will result in deterioration of product quality or an open from deterioration due to corrosion of product electrode, etc. We will not bear any responsibility for use under these environments.

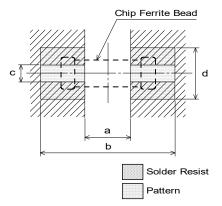
10. Notice

This product is designed for solder mounting.

Please consult us in advance for applying other mounting method such as conductive adhesive.

10-1. Land pattern designing

• Standard land dimensions (Flow and Reflow soldering)



Rated Current (A)	а	b	С	Land pad thickness and dimension d
10	2.2	4.4	2.05	4.0(85°C max) 8.0(125°C max)

(in mm)

10-2. Soldering Conditions

Products can be applied to reflow and flow soldering.

(1) Flux, Solder

Flux	Use rosin-based flux, but not highly acidic flux (with chlorine content exceeding 0.2(wt)%.)
	Do not use water-soluble flux.
Solder	Use Sn-3.0Ag-0.5Cu solder
	Standard thickness of solder paste : 100 μm to 200 μm

(2) Soldering conditions

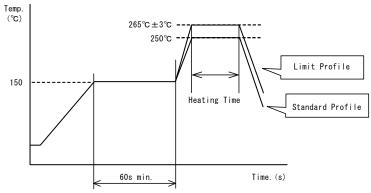
 Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.

Insufficient pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

Standard soldering profile and the limit soldering profile is as follows.
 The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.

(3) soldering profile

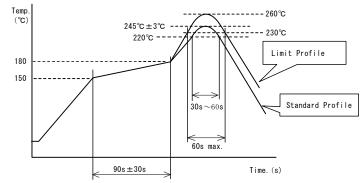
☐Flow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C、60s min.	
Heating	250°C、4∼6s	265°C±3°C、5s max.
Cycle of flow	2 times	2 times

^{*}The excessive heat by land pads may cause deterioration at joint of products with substrate.

☐Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150~180°C 、90s±30s	
Heating	above 220°C、30s∼60s	above 230°C、60s max.
Peak temperature	245±3°C	260°C,10s
Cycle of reflow	2 times	2 times

10-3. Reworking with soldering iron

Pre-heating: 150°C, 1 min
Soldering iron output: 80W max.

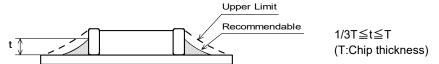
• Tip temperature: 350° C max. • Tip diameter: ϕ 3mm max.

• Soldering time : 3(+1,-0) seconds. • Times : 2times max.

Note :Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

10-4. Solder Volume

Solder shall be used not to be exceed as shown below.

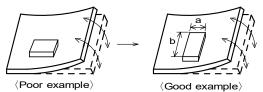


Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

10-5. Attention regarding P.C.B. bending

The following shall be considered when designing and laying out P.C.B.'s.

(1) P.C.B. shall be designed so that products are not subject to the mechanical stress for board warpage. <Products direction>



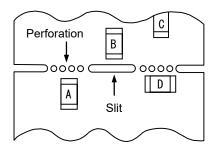
Products shall be located in the sideways direction (Length:a<b) to the mechanical stress.



(2)Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board. It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

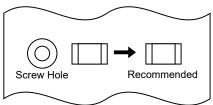
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D*1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation. If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

(3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



10-6. Mounting density

Add special attention to radiating heat of products when mounting the inductor near the products with heating. The excessive heat by other products may cause deterioration at joint of this product with substrate.

10-7. Operating Environment

Do not use this product under the following environmental conditions, on deterioration of the Insulation Resistance of the Ferrite material and/or corrosion of Inner Electrode may result from the use.

- (1) in the corrodible atmosphere such as acidic gases, alkaline gases, chlorine, sulfur gases, organic gases and etc. (the sea breeze, Cl₂, H₂S, NH₃, SO₂, NO₂,etc)
- (2) in the atmosphere where liquid such as organic solvent, may splash on the products.
- (3) in the atmosphere where the temperature / humidity changes rapidly and it is easy to dew.

10-8. Resin coating

The impedance value may change and/or it may affect on the product's performance due to high cure-stress of resin to be used for coating / molding products. So please pay your careful attention when you select resin. In prior to use, please make the reliability evaluation with the product mounted in your application set.

10-9. Cleaning

Excessive ultrasonic oscillation during cleaning can cause the PCBs to resonate, resulting in cracked chips or broken solder joints. Before starting your production process, test your cleaning equipment / process to insure it does not degrade this product.



10-10. Handling of a substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.

Bending

Twisting



10-11. Storage Conditions

(1) Storage period

Use the products within 6 months after delivered.

Solderability should be checked if this period is exceeded.

(2) Storage conditions

• Products should be stored the warehouse on the following conditions.

Temperature: -10°C to 40°C

Humidity : 15% to 85% relative humidity No rapid change on temperature and humidity

- Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- Avoid storing the product by itself bare (i.e. exposed directly to air).
- (3) Delivery

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

11. /!\ Note

- (1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2)You are requested not to use our product deviating from the agreed specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.